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(12) **United States Design Patent**
Feng

(10) **Patent No.:** **US D745,474 S**
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- (54) **LIGHT EMITTING DIODE CHIP**
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- (52) **U.S. Cl.**
USPC **D13/180**

- (58) **Field of Classification Search**
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H01L 27/156; H01L 31/02; H01L 33/00;
H01L 33/0079; H01L 33/04; H01L 33/08;
H01L 33/10; H01L 33/20; H01L 33/38;
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H01L 33/486; H01L 24/06; H01J 3/021;
H01S 5/34; F21K 9/00; F21K 9/30; F21K
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See application file for complete search history.

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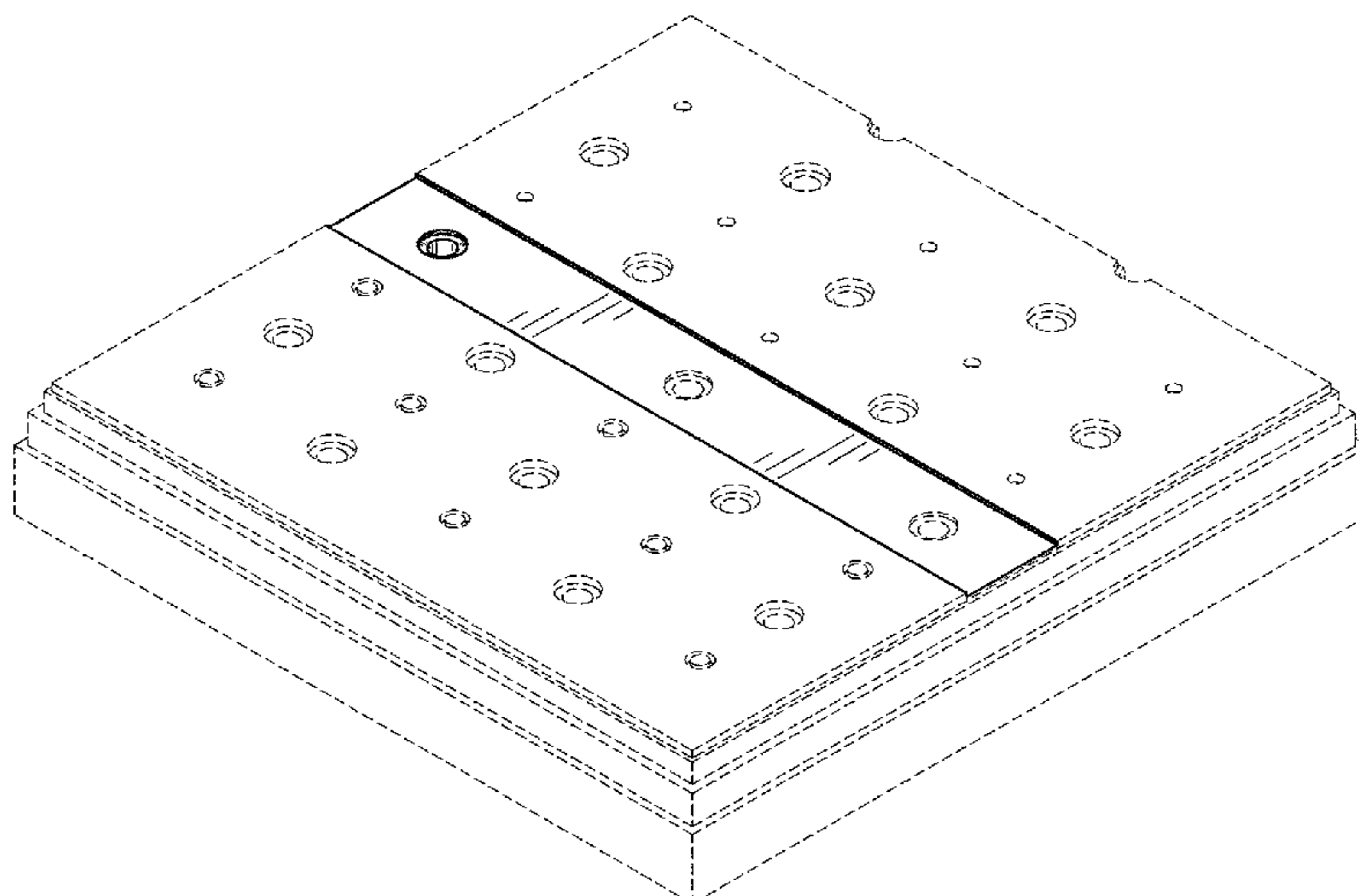
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(57) **CLAIM**
The ornamental design for a light emitting diode chip, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a light emitting diode chip showing an embodiment of my new design;
FIG. 2 is a front view of the embodiment;
FIG. 3 is a rear view of the embodiment;
FIG. 4 is a left side view of the embodiment;
FIG. 5 is a right side view of the embodiment;
FIG. 6 is a top view of the embodiment; and,
FIG. 7 is a bottom view of the embodiment.
The broken line portions of the light emitting diode chip in FIGS. 1-7 represent unclaimed portions of the design and form no part thereof.

1 Claim, 5 Drawing Sheets



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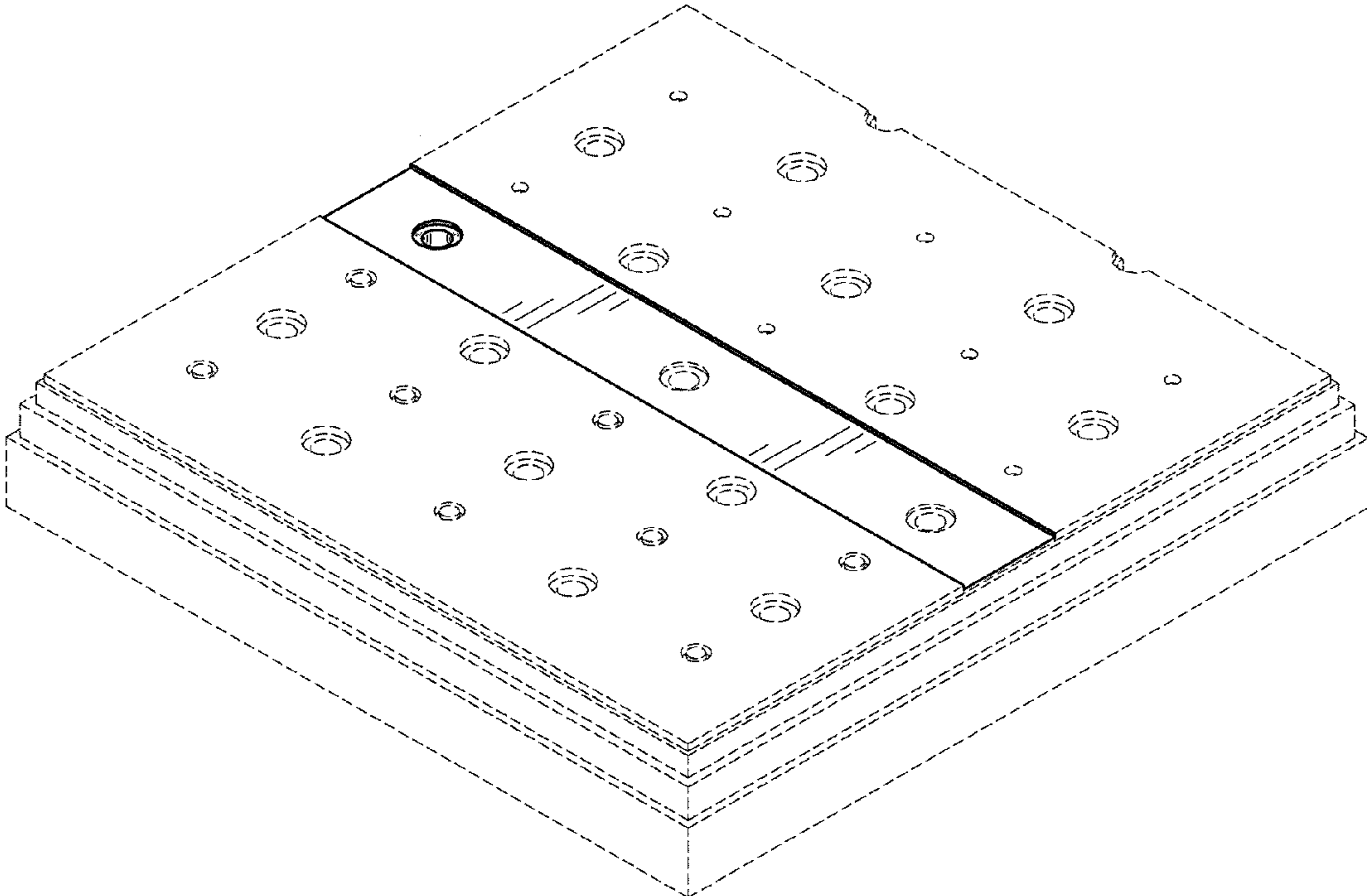


FIG. 1

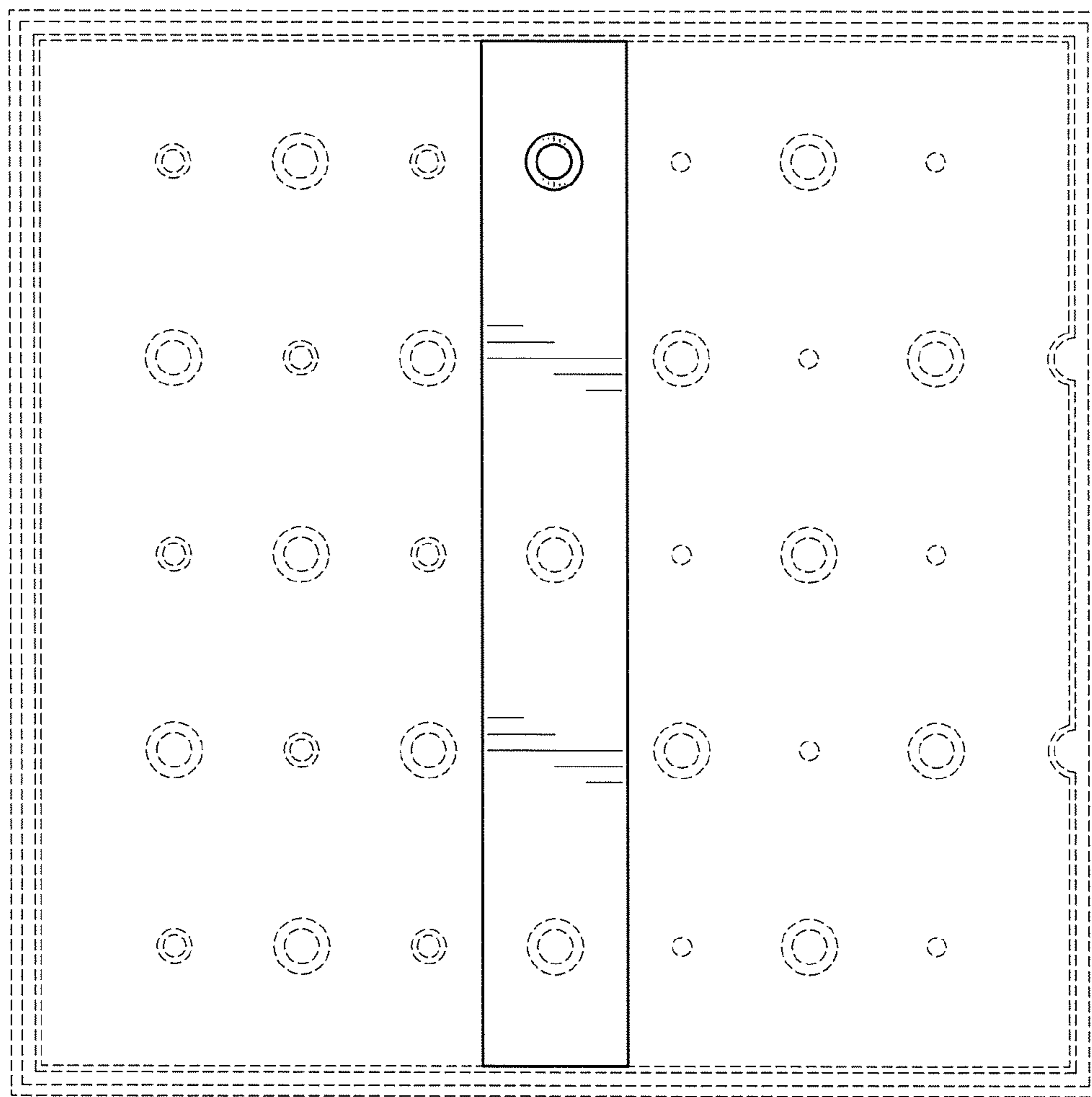


FIG. 2

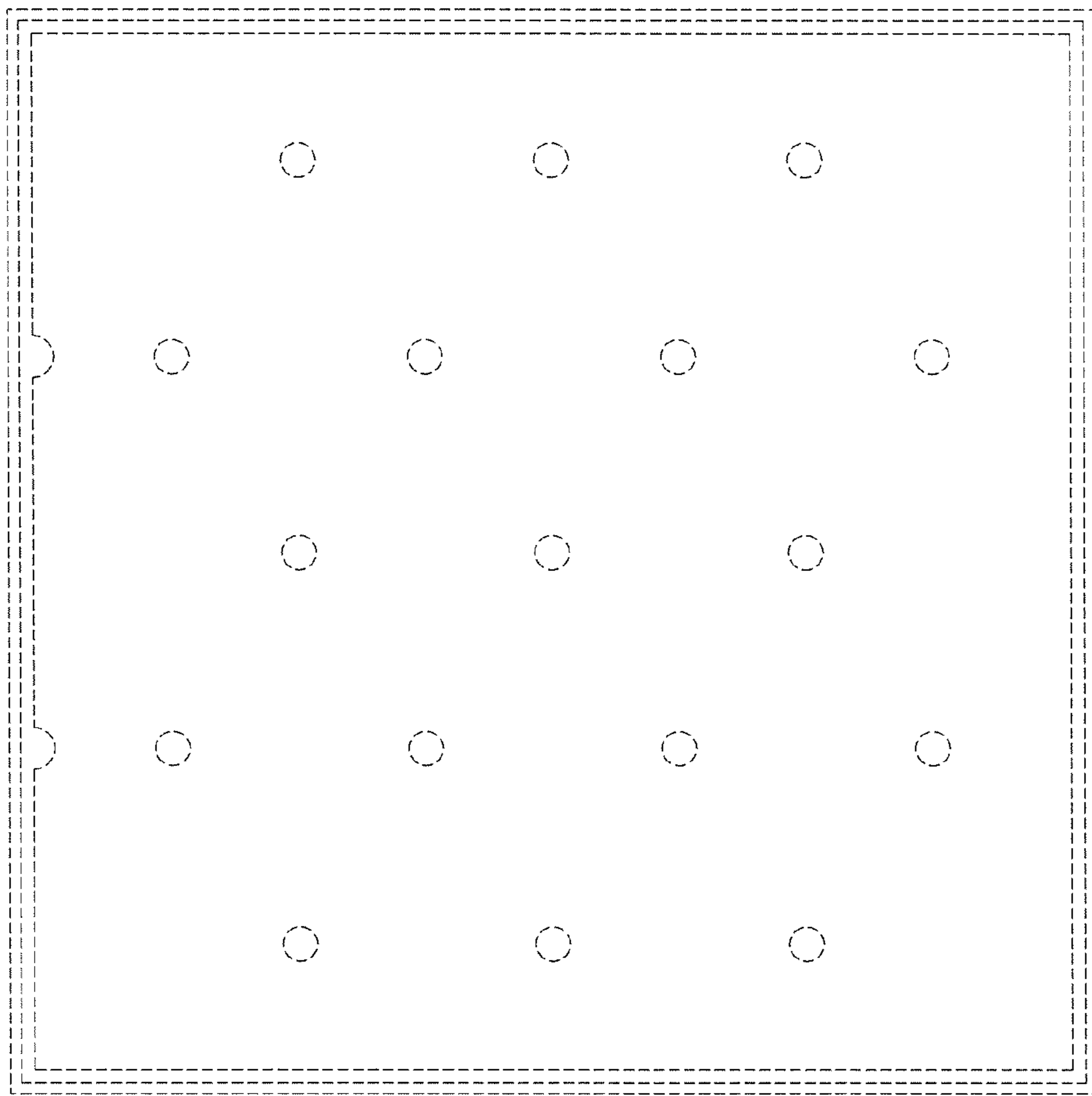


FIG. 3

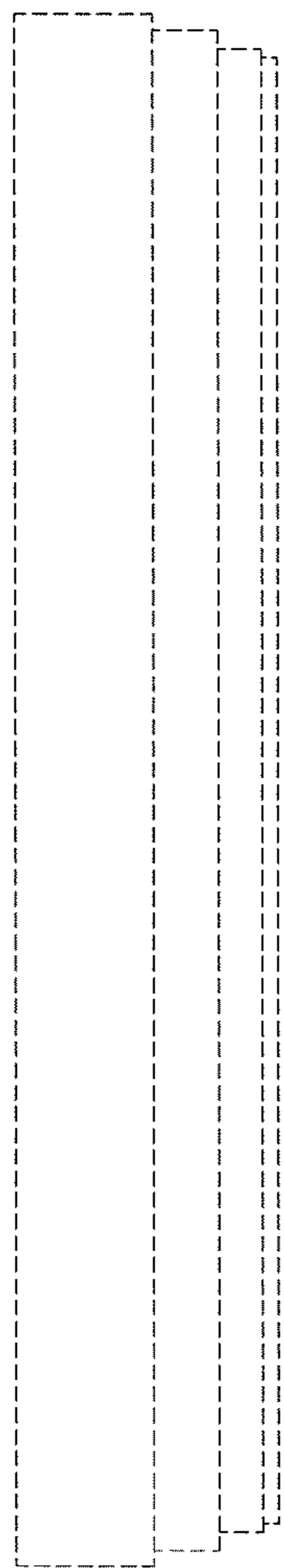


FIG. 4

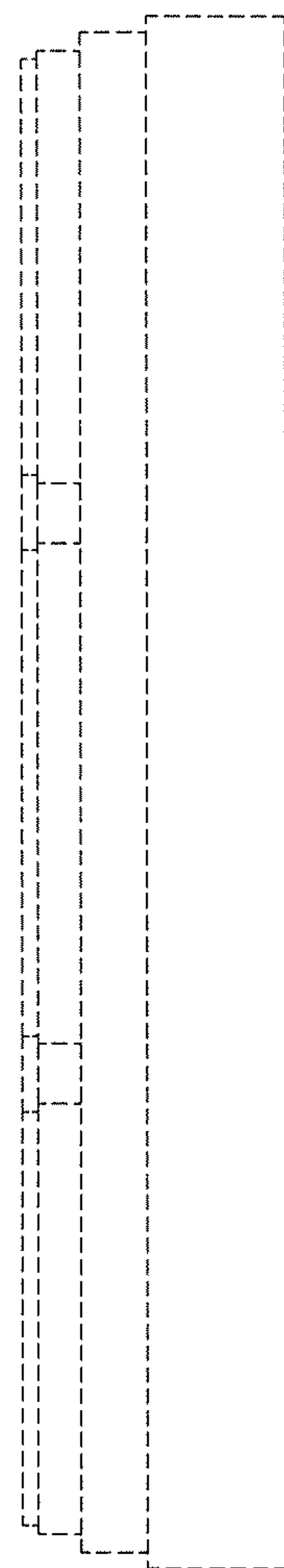


FIG. 5

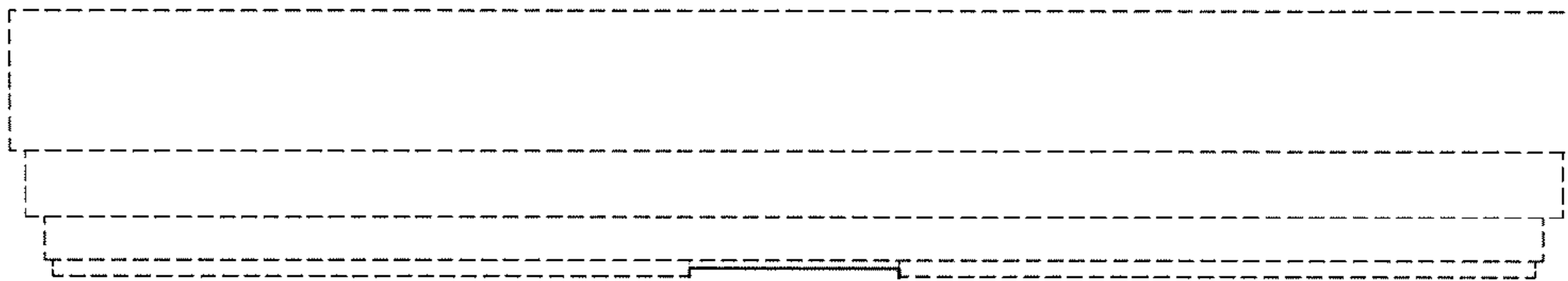


FIG. 6

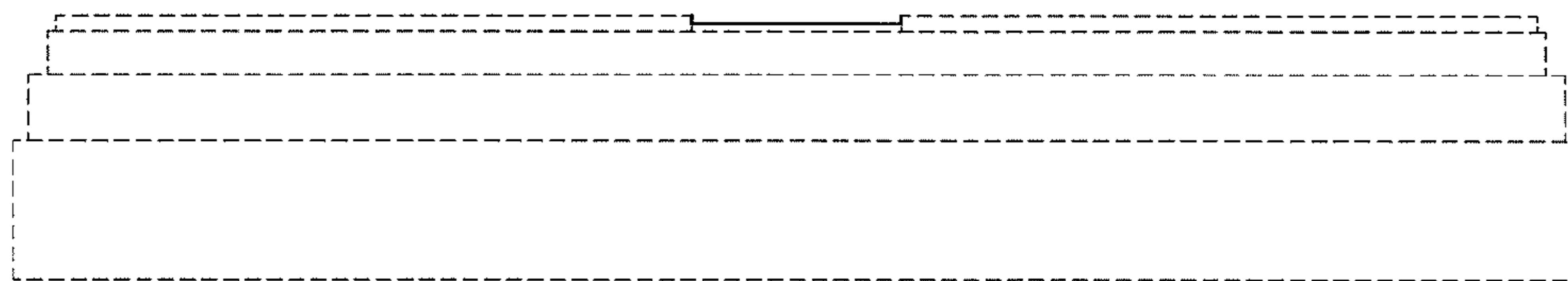


FIG. 7